



259/014

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of

Gu-Sung KIM

Examiner: Long Pham

Serial No.: 10/073,173

Group Art Unit: 2814

Filed: February 13, 2002

Confirmation No. 4677

For: WAFER LEVEL PACKAGE WITH AIR PADS
AND MANUFACTURING METHOD THEREOF

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §1.56

Commissioner for Patents
P.O. Box 1450
Alexandria, VA. 22313-1450

Sir:

Submitted herewith on Form PTO-1449 is a listing of documents known to applicant in order to comply with applicant's duty of disclosure pursuant to 37 C.F.R. §1.56. A copy of the listed documents is being submitted to comply with the provisions of 37 C.F.R. §§1.97 & 1.98.

The submission of any document herewith, which is not a statutory bar, is not intended as an admission that such document constitutes prior art against the claims of the present application. Applicant does not waive any rights to take any action which would be appropriate to antedate or otherwise remove as a competent reference any document which is determined to be a prima facie prior art reference against the claims of the present application.

RECEIVED
JUL 30 2003
TECHNOLOGY CENTER 2800


CONCISE EXPLANATION OF
RELEVANCE OF EACH DOCUMENT

The listed documents are being submitted in compliance with 37 C.F.R. 1.97(c) submission after the mailing of a Final Rejection. Enclosed is the necessary fee as set forth in 1.17(p).

Applicant respectfully requests that the listed documents be considered by the Examiner and be made of record in the present application and that an initialed copy of Form PTO-1449 be returned in accordance with MPEP §609.

Respectfully submitted,

Date: July 25, 2003


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PETITION and DEPOSIT ACCOUNT CHARGE AUTHORIZATION

This document and any concurrently filed papers are believed to be timely. Should any extension of the term be required, applicant hereby petitions the Director for such extension and requests that any applicable petition fee be charged to Deposit Account No. 50-1645.

If fee payment is enclosed, this amount is believed to be correct. However, the Director is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-1645.

Any additional fee(s) necessary to effect the proper and timely filing of the the accompanying-papers may also be charged to Deposit Account No. 50-1645.

U.S. DEPARTMENT OF COMMERCE



ATTY DOCKET NO.
259/014

SERIAL NO.
10/073,173

APPLICANT
Gu Sung KIM

FILING DATE
February 13, 2002

GROUP
2814

U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO

OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

			KOHL, Paul A.; MARTIN, Kevin, "Wafer-Level Packaging Addresses Chip-to-Module Interconnections"
			Semiconductor International, CAHNERS Business Information, Reed Elsevier, Inc. (April 2001)
			KOHL, Paul A., et al, "Air-Gaps for Electrical Interconnections": Electrochemical and Solid-State
			Letters, 1(1):49-51, The Electrochemical Society, Inc. (1998)

EXAMINER

DATE CONSIDERED

IPT-212(a):4/90